

ON Semiconductor®

FDBL86563-F085

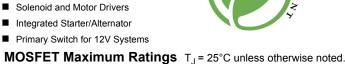
N-Channel PowerTrench® MOSFET **60 V, 240 A, 1.5 m**Ω

Features

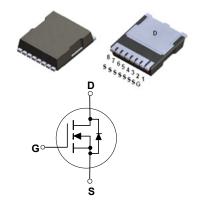
- Typical $R_{DS(on)}$ = 1.1 m Ω at V_{GS} = 10V, I_D = 80 A
- Typical $Q_{q(tot)}$ = 130 nC at V_{GS} = 10V, I_D = 80 A
- UIS Capability
- RoHS Compliant
- Qualified to AEC Q101

Applications

- Automotive Engine Control
- PowerTrain Management







Symbol	Parameter		Ratings	Units
V_{DSS}	Drain-to-Source Voltage		60	V
V_{GS}	Gate-to-Source Voltage		±20	V
	Drain Current - Continuous (V _{GS} =10) (Note 1) T _C = 25°C		240	А
ID	Pulsed Drain Current	T _C = 25°C	See Figure 4	^
E _{AS}	Single Pulse Avalanche Energy	(Note 2)	614	mJ
D	Power Dissipation		357	W
P_D	Derate Above 25°C		2.38	W/°C
T _J , T _{STG}	Operating and Storage Temperature		-55 to + 175	°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case		0.42	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	(Note 3)	43	°C/W

- 2: Starting $T_J = 25^{\circ}C$, L = 0.3mH, $I_{AS} = 64$ A, $V_{DD} = 60$ V during inductor charging and $V_{DD} = 0$ V during time in avalanche.
- 3: R_{0,JA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design, while $R_{\theta JA}$ is determined by the board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDBL86563	FDBL86563-F085	MO-299A	13"	24mm	2000 units

Max.

Min.

Тур.

Units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted.

Parameter

Off Characteristics							
B _{VDSS}	Drain-to-Source Breakdown Voltage	$I_D = 250 \mu A$	60	-	-	V	
ı	Drain-to-Source Leakage Current	V _{DS} =60V,	$T_{\rm J} = 25^{\rm o}{\rm C}$	-	-	1	μА
IDSS		$V_{GS} = 0V$	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	-	1	mA
I _{GSS}	Gate-to-Source Leakage Current	V _{GS} = ±20V		-	-	±100	nA

Test Conditions

On Characteristics

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$		2.0	2.9	4.0	V
R _{DS(on)}	Drain to Source On Resistance	I _D = 80A,	$T_{J} = 25^{\circ}C$	-	1.1	1.5	mΩ
		V _{GS} = 10V	T _J = 175°C (Note 4)	-	2.1	2.9	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	$V_{DS} = 30V, V_{GS} = 0V,$ f = 1MHz		-	10300	-	pF
C _{oss}	Output Capacitance			-	2590	-	pF
C _{rss}	Reverse Transfer Capacitance			-	270	-	pF
R_g	Gate Resistance	f = 1MHz		-	4.3	-	Ω
$Q_{g(ToT)}$	Total Gate Charge at 10V	$V_{GS} = 0$ to 10V	V _{DD} = 48V	-	130	169	nC
$Q_{g(th)}$	Threshold Gate Charge	$V_{GS} = 0 \text{ to } 2V$ $I_D = 80A$		-	19	-	nC
Q_{gs}	Gate-to-Source Gate Charge		_	-	48	-	nC
Q_{gd}	Gate-to-Drain "Miller" Charge			-	20	-	nC

Switching Characteristics

t _{on}	Turn-On Time		-	-	160	ns
t _{d(on)}	Turn-On Delay		-	30	-	ns
t _r	Rise Time	V _{DD} = 30V, I _D = 80A,	-	77	-	ns
t _{d(off)}	Turn-Off Delay	V_{GS} = 10V, R_{GEN} = 6Ω	-	78	-	ns
t _f	Fall Time		-	57	-	ns
t _{off}	Turn-Off Time		-	-	200	ns

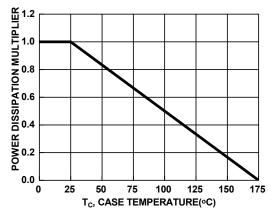
Drain-Source Diode Characteristics

V _{SD}	ISOURCE-TO-Drain Dione Voltage	I _{SD} =80A, V _{GS} = 0V	-	-	1.25	V
		I_{SD} = 40A, V_{GS} = 0V	-	-	1.2	V
t _{rr}	Reverse-Recovery Time	$I_F = 80A$, $dI_{SD}/dt = 100A/\mu s$,	-	94	140	ns
Q _{rr}	Reverse-Recovery Charge	V _{DD} =48V	-	131	200	nC

Note:

4: The maximum value is specified by design at T_J = 175°C. Product is not tested to this condition in production.

Typical Characteristics



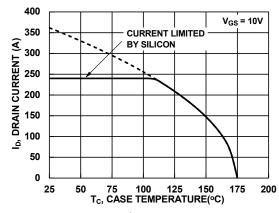


Figure 1. Normalized Power Dissipation vs. Case Temperature

Figure 2. Maximum Continuous Drain Current vs.
Case Temperature

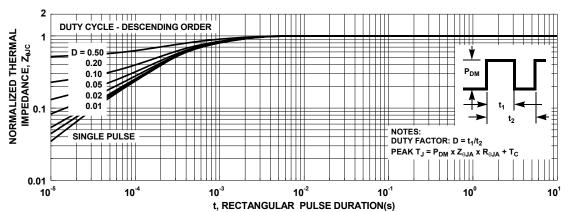


Figure 3. Normalized Maximum Transient Thermal Impedance

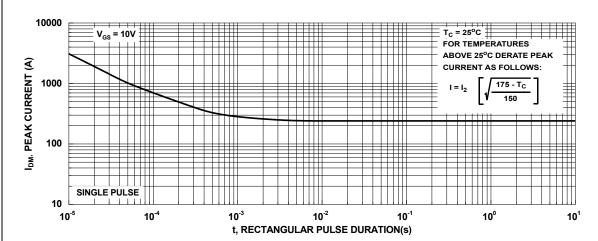


Figure 4. Peak Current Capability

Typical Characteristics

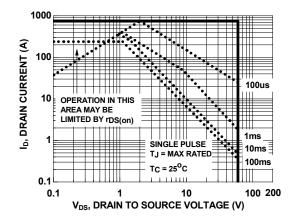
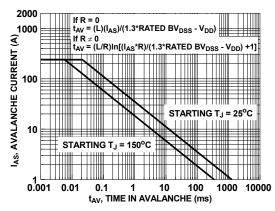


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to ON Semiconductor Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching Capability

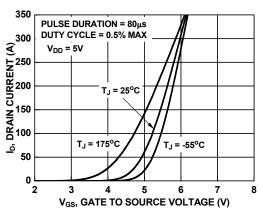


Figure 7. Transfer Characteristics

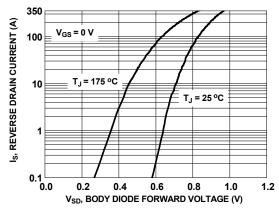


Figure 8. Forward Diode Characteristics

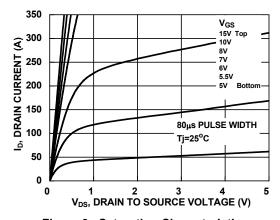


Figure 9. Saturation Characteristics

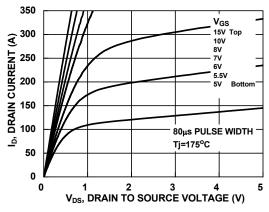


Figure 10. Saturation Characteristics

Typical Characteristics

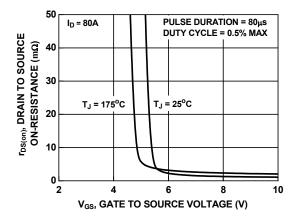


Figure 11. R_{DSON} vs. Gate Voltage

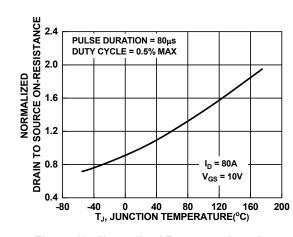


Figure 12. Normalized R_{DSON} vs. Junction Temperature

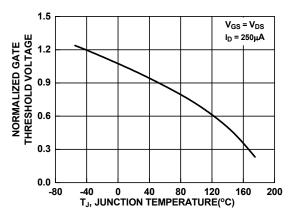


Figure 13. Normalized Gate Threshold Voltage vs. Temperature

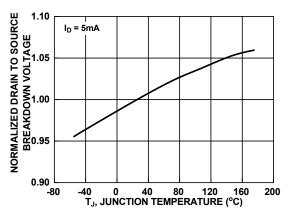


Figure 14. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

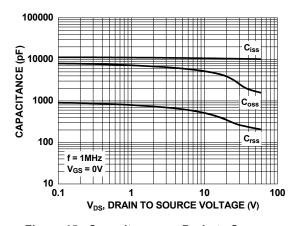


Figure 15. Capacitance vs. Drain to Source Voltage

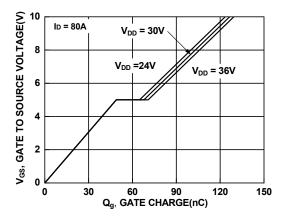


Figure 16. Gate Charge vs. Gate to Source Voltage

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